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A5-1 Effect of Overcoating SiO Thin Films on Monolithic

Elastic Surface Wave Amplifiers

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Variations in conductance of thin films of InSb with thickness of vacuum-deposited overlay of SiO thin film indicate surface depletion or enhancement in semiconfuctors by substrate temperatures. These films are applied in the construction of monolithic elastic surface wave amplifiers.

Thin film structures several hundred angstroms thick of InSb on LiNbO₃ substrate have been applied in the construction of monolithic elastic surface wave amplifiers^{1,2} We report herein that vacuum-deposited SiO causes an enhancement of layers at the substrate temperatures of about 95°C and a depletion of layers at about 300°C on the surface of InSb thin films. Also, monolithic elastic surface wave amplifiers with useful gain and output power were obtainable by using this new method.

To demonstrate charge depletion or enhancement by substrate temperatures, a series of InSb films about 500Å thick were vacuum deposited by source temperature-programed evaporation² from high-purity, n-type InSb ($N_D=10^{14}/cm^3$) onto a mica plate which was maintained at a temperature of 280°C during deposition and annealed in a vacuum at 340°C. The evaporation equipment has a mesh between the source and the substrate because of removing a rich In gas.

The variation of σ h of the InSb film with thickness of an SiO insulating layer is shown in Fig.l with the substrate temperature as a parameter, where σ is conductivity and h is film thickness. We found that σ h decreased at the substrate temperature of about 300°C and that it increased at about 95°C. A similar phenomenon has been explained from the variation of the depth and amount of charge depletion at the surface of an InSb thin film semiconductor by SiO and CaF³₂; however, our phenomenon cannot be explained by this theory since it was caused by variations of the substrate temperature.

These films are applied in monolithic elastic surface wave amplifiers. First, a thin barrier layer of SiO was deposited on a 131° -rotated, Y-cut, X-propagation LiNbO₃ substrate (effective electromechanical coupling coefficient, K²=0.055). The InSb film was then evaporated by source temperature-programed evaporation². Finally, the structure was overcoated with SiO by the method formerly described.

The sample without an overcoating by SiO thin film in Fig.2 has a small value of $\sigma h=12.3 \mu U$ and rather small value of hole mobility, $\mu_{h}=792 \text{ cm}^2/\text{V}\cdot\text{sec}$, and reveals a small gain only at the frequency of 39.5MHz. By overcoating SiO thin film at the

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substrate temperature of about 95°C, the electric properties of InSb thin film were extremely improved; that is, the oh changes in 40.2µU from 12.3µU, and the hole mobility changes in 2068cm²/V·sec with a drift mobility of 1600cm²/V·sec from 792cm²/ V-sec. Further, a net terminal gain of 40dB with an electronic gain of 70dB was obtained at 195MHz.

Figure 3 shows the characteristic of another sample. The oh of InSb thin film without overcoating by SiO thin film was rather large for the device and was $145\mu U$. By overcoating SiO thin film at the substrate temperature of about 300 C, the σh of InSb thin film decreased in 93µU and the gain was improved.

The sample without overcoating by SiO thin film in Fig.4 has a very small value of $\sigma h=8.7\mu U$, and indicates only interaction between a hole carrier and the elastic surface wave. The σ h increases in 16.5 μ U by overcoating SiO thin film at around 95 C, and the device shows interaction between an electron carrier and surface wave.

In conclusion, we have shown that the effect of overcoating SiO thin films at various temperatures can be useful in producing monolithic elastic surface wave amplifiers, although we cannot yet fully explain this phenomenon physically.

Reference

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